

DEC 10 2002  
PATENT & TRADEMARK OFFICE

AF/1700  
PATENT

Case Docket No. IIDAP10.001AUS  
Date: December 6, 2002  
Page 1

In re application of : Miyoshi, et al.  
App. No. : 09/844,155  
Filed : April 27, 2001  
For : COPPER ALLOY SUITABLE  
FOR AN IC LEAD PIN FOR A  
PIN GRID ARRAY PROVIDED  
ON A PLASTIC SUBSTRATE  
Examiner : Ip, Sikyin  
Art Unit : 1742

) I hereby certify that this correspondence and all  
marked attachments are being deposited with the  
United States Postal Service as first class mail in an  
envelope addressed to: United States Patent and  
Trademark Office, P.O. Box 2327, Arlington, VA  
22202, on  
12/6/02  
(Date)  
Thomas R. Arno, Reg. No. 40,490

UNITED STATES PATENT AND TRADEMARK OFFICE BOX AF  
P.O. Box 2327  
Arlington, VA 22202

RECEIVED

DEC 12 2002

TC 1700

Sir:

Transmitted herewith is an Amendment after Final in the above-identified application.

An extension of time to respond for 1 month is hereby requested.

Time Extension Fee:

one month (\$110 large entity)

Return prepaid postcard.

A check in the amount of \$110 is enclosed.

Please charge any additional fees, including any fees for additional extension of time, or credit overpayment to Deposit Account No. 11-1410.

Please use Customer No. 20,995 for the correspondence address.

12/11/2002 SDENBOB1 00000049 09844155

01 FC:1251

110.00 OP

  
Thomas R. Arno  
Registration No. 40,490  
Attorney of Record  
Customer No. 20,995  
(619) 235-8550

S:\DOCS\JOHJOH-2829.DOC:dmn  
120602

IIDAP10.001AUS



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant :	Miyoshi, et al.	) Group Art Unit 1742
Appl. No. :	09/844,155	)
Filed :	April 27, 2001	)
For :	COPPER ALLOY SUITABLE FOR AN IC LEAD PIN FOR A PIN GRID ARRAY PROVIDED ON A PLASTIC SUBSTRATE	)
Examiner :	Ip, Sikyin	)

10/C  
APR

DEC 12 2002  
TC 1700 2/3/03

AMENDMENT AFTER FINAL

United States Patent and Trademark Office  
P.O. Box 2327  
Arlington, VA 22202

Dear Sir:

In response to the Office Action dated August 7, 2002, please amend the above captioned patent application as set forth below.

IN THE CLAIMS:

Please amend Claims 1-4 as follows:

1. (Amended) A copper alloy suitable for an IC lead pin for a pin grid array provided on a plastic substrate, wherein the copper alloy is selected from the group consisting of:  
a copper alloy consisting of 0.05 to 0.5 wt% of Zn and 0.05 to 0.5 wt% of Mg, with the balance being made of unavoidable impurities and Cu;  
a copper alloy consisting of 0.1 to 1.0 wt% of Sn, with the balance being made of unavoidable impurities and Cu; and  
a copper alloy consisting of 0.1 to 1.0 wt% of Sn and 0.1 to 0.6 wt% of Ag, with the balance being made of unavoidable impurities and Cu;  
wherein the copper alloy has conductivity of 50% IACS or more, and tensile stress of 400 MPa or more but 650 MPa or less.